



Product Change Notification

Change Notification #: 118484-00

Change Title: Select Intel® SSD D7-P5510 Series PCN 118484-00, Product Material, Adding Nanya C-die and Hynix DRAM as 2nd Source

Date of Publication: September 14, 2021

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material	December 17, 2021
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Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following changes.

1. Current DRAM IPN# J87850-001 EOL-ing (Nanya) and changing to new IPN# J87850-002 (Nanya), affect ADPR SE SFF 3.8T
2. Current DRAM IPN# K92222-001 EOL-ing (Samsung) and changing to new IPN# K92222-002 (Hynix), affected ADPR SE 7.6T

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD D7-P5510 Series (3.84TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic Single Pack OPAL	SSDPF2KX038TZOS	99A5CZ
Intel® SSD D7-P5510 Series (7.68TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic Single Pack OPAL	SSDPF2KX076TZOS	99A5D1
Intel® SSD D7-P5510 Series (3.84TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic Single Pack	SSDPF2KX038TZ01	99A5DP
Intel® SSD D7-P5510 Series (7.68TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic Single Pack	SSDPF2KX076TZ01	99A5DR
Intel® SSD D7-P5510 Series (3.84TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic 50 Pack	SSDPF2KX038TZ	99AJR9
Intel® SSD D7-P5510 Series (7.68TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic 50 Pack	SSDPF2KX076TZ	99AJRA

PCN Revision History:

Date of Revision:

September 14, 2021

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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